

Super high maximum on-state currents in 2D transistors

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Two-dimensional (2D) materials have been recognized as a type of potential channel material to replace silicon in future field-effect transistors (FETs) by the International Technology Roadmap for Semiconductors (ITRS) and its successor the International Roadmap for Devices and Systems (IRDS)^[1–4]. Substantial first principle quantum transport simulations have predicted that many 2D transistors, including those with MoS₂, WSe₂, phosphorene, and Bi₂O₂Se channels, own excellent device performance and are able to extend Moore's law down to the sub-10 nm scale^[4]. However, the actual 2D transistors suffer from poor contact and dielectric^[4]. As a result, the maximum on-state currents ($I_{\text{on}}^{\text{max}}$) or saturation currents (I_{sat}) of the fabricated 2D transistors are even generally lower than the on-state current (I_{on}) (>1200 $\mu\text{A}/\mu\text{m}$) of the most advanced silicon transistors. As we know, the on-state current is one of the most critical figure of merit of a FET required by ITRS and IRDS, and a large on-state current implies a fast switching speed.

Due to lack of reliable and sustainable doping technique, 2D semiconductors often need to contact metal electrodes directly. Schottky barrier is often generated at the metal–semiconductor interface, resulting a poor contact. Schottky barrier originates from the the Fermi level pinning (FLP), which is caused by metal-induced gap states (MIGS)^[3]. Because the Fermi level of semimetal Bi aligns with the conduction of the monolayer (ML) MoS₂, the MIGS and thus FLP are greatly depressed at the interface between Bi and ML MoS₂^[5]. With semimetal Bi as electrodes, Ohmic contact with ultra-low contact resistance of 123 $\Omega\cdot\mu\text{m}$ and an $I_{\text{on}}^{\text{max}}$ up to 1135 $\mu\text{A}/\mu\text{m}$ are obtained in a ML MoS₂ transistor by Kong *et al.* from MIT in 2021^[5]. Compared with the ML MoS₂, bilayer (BL) MoS₂ has a narrower bandgap and higher electron density, which is beneficial for the on-state current enhancement. Recently, Wang's group from Najing University has fab-

ricated the BL MoS₂ field-effect transistors with Bi as electrodes, and the mobility has improved by 37.9% and reached 122.6 $\text{cm}^2/(\text{V}\cdot\text{s})$, and $I_{\text{on}}^{\text{max}}$ is further increased to 1270 $\mu\text{A}/\mu\text{m}$ ^[6]. The $I_{\text{on}}^{\text{max}}$ values of these MoS₂ transistors are consistent with that (~1200 $\mu\text{A}/\mu\text{m}$) predicted based on the ab initio quantum transport simulation for the ML MoS₂ transistor by Lu *et al.* from Peking University^[7].

Very recently, a record $I_{\text{on}}^{\text{max}}$ of 1720 $\mu\text{A}/\mu\text{m}$ among all the current 2D-material transistors (Fig. 1) accompanied by a small on-state resistance of 500 $\Omega\cdot\mu\text{m}$ is achieved by Duan's group from Hunan University in the 20 nm-channel-length BL WSe₂ transistor with van der Waals (vdW) VSe₂ contact^[8]. $I_{\text{on}}^{\text{max}}$ is 1360 $\mu\text{A}/\mu\text{m}$ under $V_{\text{ds}} = 0.8$ V, which is also close to a prediction (~1500 $\mu\text{A}/\mu\text{m}$) for the ML WSe₂ MOSFET at $V_{\text{ds}} = 0.72$ V based on the ab initio quantum transport simulation by Lu *et al.*^[9]. Such a high performance can be ascribed to depression of the FLP in weak vdW contact^[3].

Although such $I_{\text{on}}^{\text{max}}$ values in the 2D MoS₂ and WSe₂ transistors are comparable with or even exceeds I_{on} in the Si transistors, it does not imply that the 2D transistors have outperformed the Si transistors as the carbon nanotube transistors do, reported by Peng *et al.*^[10]. The reason lies in the fact that the high $I_{\text{on}}^{\text{max}}$ values of the best 2D WSe₂ and MoS₂ transistors are generated in a rather high gate swing (20–60 V)^[6, 8]. However, the Si FETs required in ITRS or IRDS operate under a small supply voltage V_{dd} (about 0.7 V)^[11, 12], and I_{on} is measured under a gate swing no more than this V_{dd} . To be specific, I_{on} is obtained under a bias V_{ds} and gate swing of $V_{\text{g}}(\text{on}) - V_{\text{g}}(\text{off})$ defined by V_{dd} (Namely, $V_{\text{ds}} = V_{\text{g}}(\text{on}) - V_{\text{g}}(\text{off}) = V_{\text{dd}}$). Given the same criterion, not only I_{on} but also the closely related maximum transconductance g_{m} of the best 2D WSe₂ and MoS₂ transistors remain much smaller than those of the Si transistors under the similar V_{dd} [0.15–5 (MoS₂ and WSe₂) vs 1000 $\mu\text{A}/\mu\text{m}$ (Si) in I_{on} and 0.13–20 (MoS₂ and WSe₂) vs 3000 $\mu\text{S}/\mu\text{m}$ (Si) in g_{m}]^[6, 8, 13].

The improvement method is to use the high- κ dielectric with ultrathin thickness and obtain an ultrasmall equivalent oxide thickness (EOT)^[11]. Duan *et al.* have tried to reduce the EOT of the bilayer WSe₂ FETs by using the 3-nm Al₂O₃/6-nm HfO₂ dielectric layer. The corresponding gate swing is

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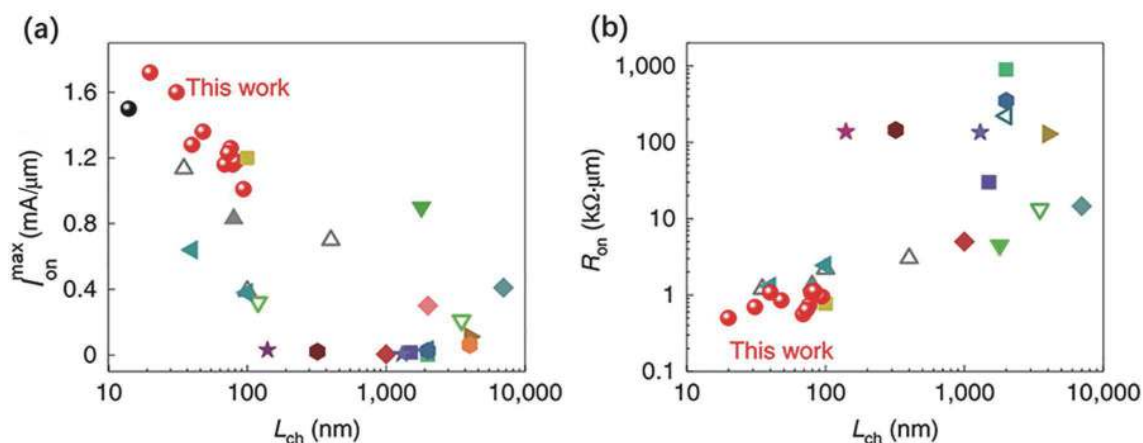


Fig. 1. (Color online) Benchmarking sub-100-nm bilayer WSe_2 transistors (red ball) against the (a) $I_{\text{on}}^{\text{max}}$ for 2D semiconductor transistors (b-P, b-As, b-AsP, MoS_2 , MoS_2 -0.7 nm, WSe_2 -0.7 nm, WS_2 , WS_2 -0.7 nm, MoTe_2 , GeAs, InSe, SnSe, ReS_2 , PtSe_2 , ZrSe_2 , HfSe_2) and I_{on} of 2021 silicon transistor (black ball) reported in ITRS, and (b) the $R_{\text{on}}^{\text{min}}$ (lowest on-state resistance) with those reported in the literature^[8]. Reproduced with permission from Springer Nature, copyright 2022.

significantly decreased from 40 to below 5 V, $I_{\text{on}}^{\text{max}}$ remains over 1 $\text{mA}/\mu\text{m}$ ^[8], and g_{m} is significantly improved from 0.13 to 150 $\mu\text{S}/\mu\text{m}$. Very recently, Peng *et al.* from Peking University have successfully fabricated the sub-0.5-nm EOT (2.3-nm $\beta\text{-Bi}_2\text{SeO}_5$) in the 2D $\text{Bi}_2\text{O}_2\text{Se}$ FETs, realizing ultralow leakage current^[14]. This achievement overcomes the challenges in depositing the ultra-thin gate dielectric on the dangling-bond-free 2D semiconductors, making it promising for the development of 2D transistors with high I_{on} and g_{m} .

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